# Fully Integrated Switched-Capacitor DC-DC Conversion

**Elad Alon** 

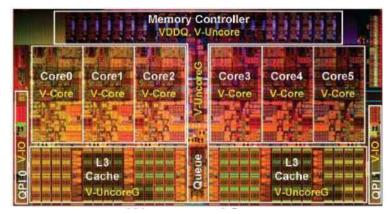
In collaboration with Hanh-Phuc Le, Seth Sanders



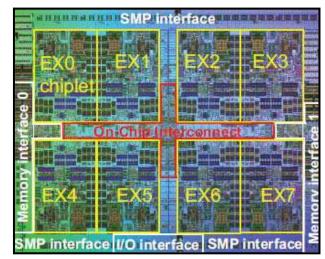
Berkeley Wireless Research Center University of California, Berkeley



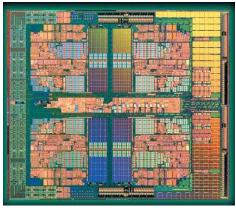
### **Multi-Core Chips Are Here**



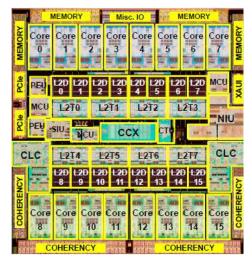
#### **Intel Westmere**



**IBM POWER7** 



#### **AMD** Phenom

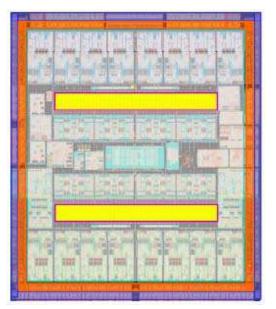


**Sun Rainbow Falls** 



# **Multi-Supply Chips?**

- Separate supply voltages clearly desirable
  - Power management, compensate variability, etc.
- But, true multi-supply adoption slow
  - Except for power gating

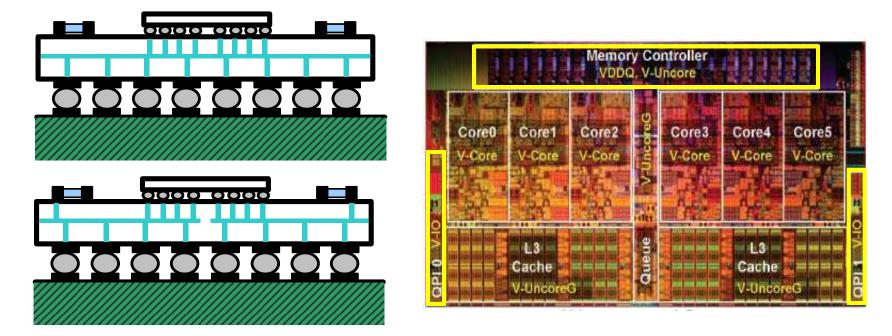


Shin, ISSCC 2010

• Why not use multiple external converters?



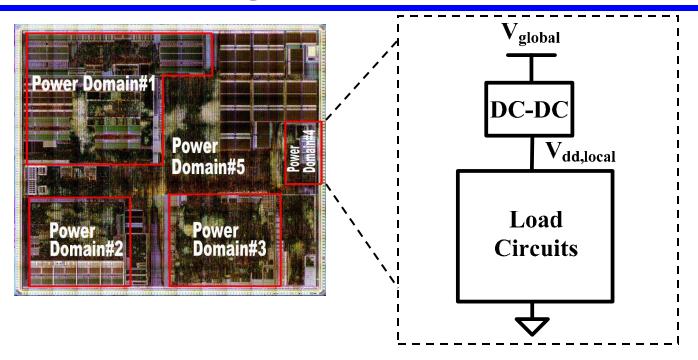
# **Supply Impedance and Split Planes**



- Supply impedance requirement extremely low
  - 1V, 100A part  $\rightarrow$  1m $\Omega$
- Split power planes bad for impedance
  - Load and decap isolation
  - Reason I/O's often placed on edges even with flip-chip



### **On-Die Voltage Conversion**

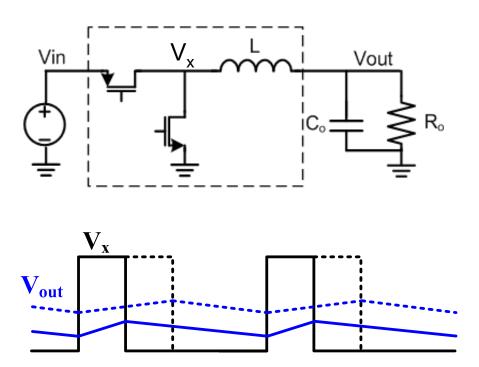


- Enables single, low-impedance global input voltage
- Key challenge: fully integrated DC-DC
  - Energy storage must be integrated on-die too



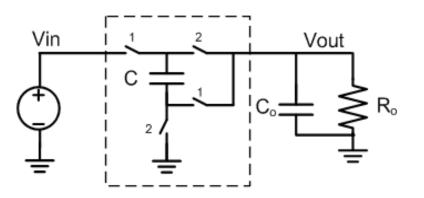
# **Switching Converter Options**

#### Inductor:



- Conversion ratio set by duty cycle
- Very popular for offchip converters

#### Capacitor:





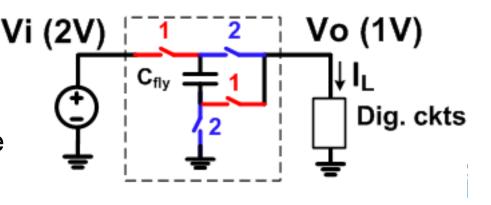


- Conversion ratio set by topology
- Many perceived disadvantages



# So Why Switched-Capacitor (SC)?

- Key motivation: integration with <u>low cost</u>
  - Dense, high-quality capacitance widely available
  - (Development of on-die magnetics can be leveraged for SC converters too)



- Integrated SC design can mitigate perceived downsides
  - Component count no longer critical
- What is achievable efficiency, power density?



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### **Selected Previous Designs**

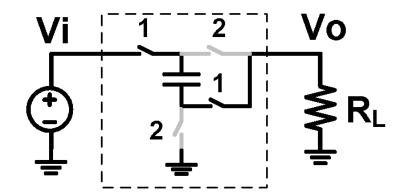
Work	Breussegem, VLSI 09	Somasekhar, VLSI 09
Technology	130nm Bulk	32nm Bulk
Тороlоду	2/1 step-up	2/1 step-up
Interleaved Phases	16	32
Converter Area (mm <sup>2</sup> )	2.25	6.678x10 <sup>-3</sup>
Power density @ η <sub>max</sub>	0.002 W/mm <sup>2</sup>	1.123 W/mm <sup>2</sup>
Efficiency (η <sub>max</sub> )	82%	60%
	EC_1FC_2EC_3FC_4 Cout EC_5FC_6FC_7FC_8	Pump 0-15 Pump 16-31

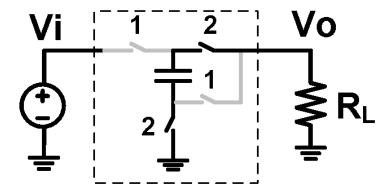


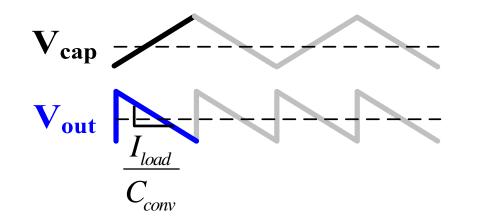
### **Review: SC Basics**

Phase 1:

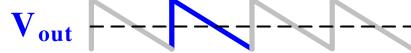










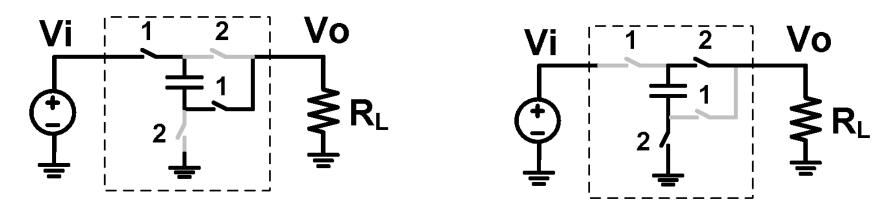




# **Switched Capacitor (SC) Basics**

Phase 1:

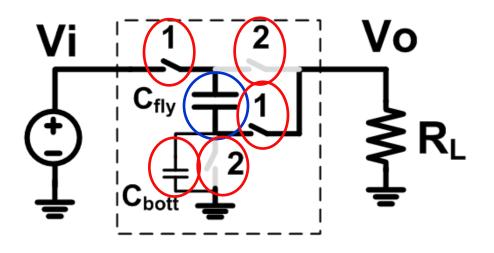




- Conversion ratio set by topology
- Works in other direction too
  - Step-up: reverse V<sub>i</sub>, V<sub>o</sub>



## **SC Converter Loss Mechanisms**



- Intrinsic loss
  - Fundamental to converter operation
- Switch/parasitic loss
  - Non-idealities of the capacitor(s) and switches

# SC Converter Loss with Digital Loads

- Gate delay depends on  $V_{dd}$ : • Performance set by  $V_{min}$ • SC converter effective output resistance (for  $V_{min}$ ):  $R_{eff,Csw} = \frac{1}{M_{conv,con}C_{conv}f_{sv}}$
- But, load also draws "extra" current when V<sub>dd</sub> > V<sub>min</sub>
  - This power is wasted since it doesn't improve performance
- Ripple leads to extra loss: *I*

$$P_{Reff} = \frac{2 I_{load}^2}{M_{conv,cap} C_{conv} f_{sw}}$$

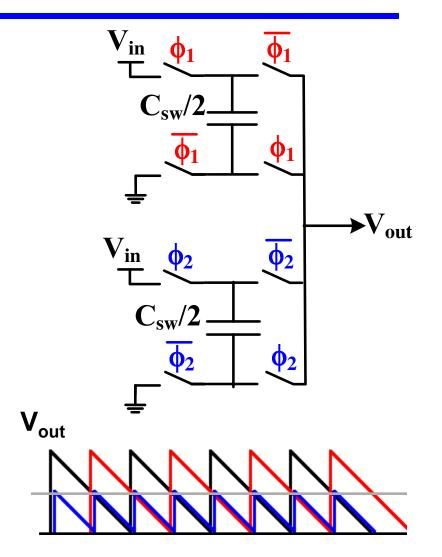


## Interleaving

- Good news: interleaving reduces ripple
  - But leaves V<sub>min</sub> unchanged
- With N<sub>int</sub> interleaved converters:

$$P_{Reff} = \left(1 + \frac{1}{N_{int}}\right) \frac{I_{load}^2}{M_{conv,cap}C_{conv}f_{sw}}$$

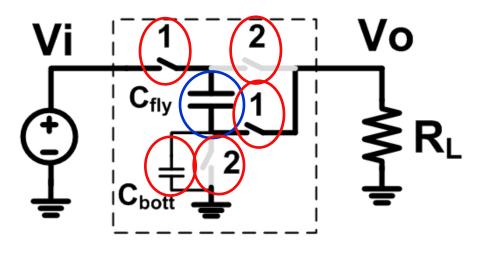
 Ripple minor for ~16+ way interleaving



D. Ma, "Robust Multiple-Phase Switched-Capacitor DC-DC with Digital Interleaving Regulation Scheme," *ISLPED* 2006.



# **Efficiency Optimization**

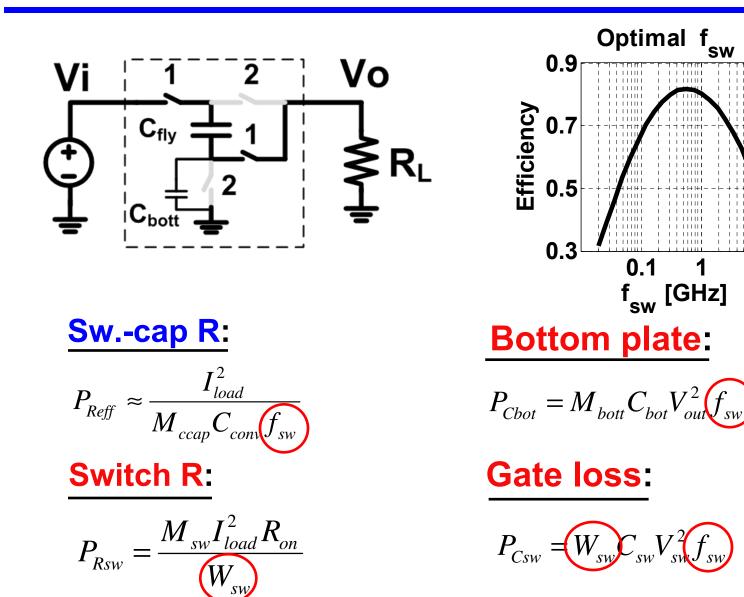


- Intrinsic loss
  - Reduced by  $\uparrow$  C density
  - Reduced by  $\uparrow f_{sw}$

- Switch/parasitic loss
  - Reduced by  $\uparrow$  switch  $f_T$
  - Increased by  $\uparrow f_{sw}$
- Efficiency optimization: choose  $f_{sw}$  and  $W_{sw}$  to balance loss terms



### Loss Terms Detail

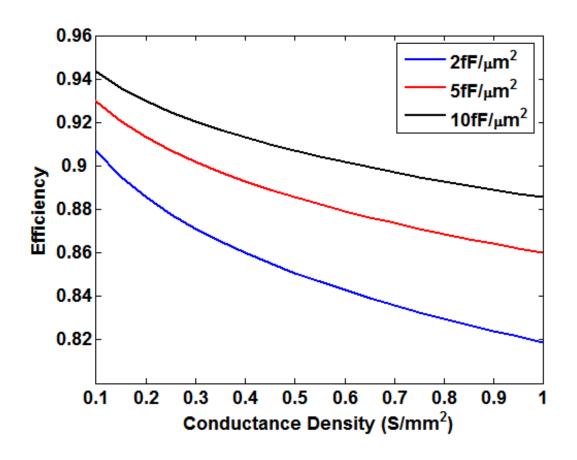




## **Optimized Efficiency**

• Ignoring bottom-plate:

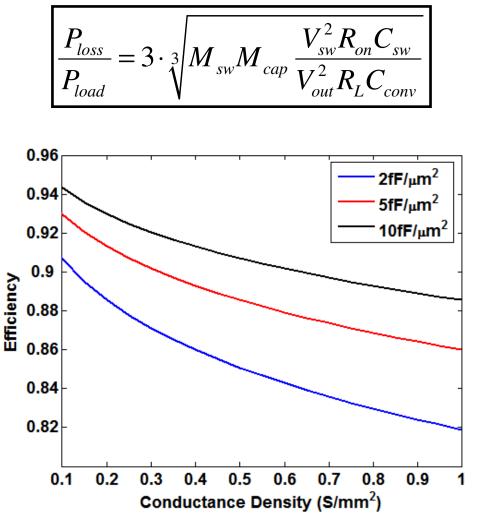
$$\frac{P_{loss}}{P_{load}} = 3 \cdot \sqrt[3]{M_{conv,sw}} M_{conv,cap} \frac{V_{sw}^2 R_{on} C_{sw}}{V_{out}^2 R_L C_{conv}}$$





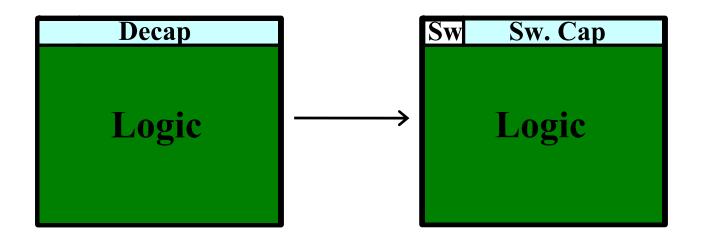
# **Optimized Efficiency** cont'd

- Efficiency set by conductance density
  - I.e.,  $(I_{load}/V_{out})$  / Conv. Area
  - (Equivalent to power density for given V<sub>out</sub>)
- Typical numbers (1V)
  - Mobile device: ~0.1 S/mm<sup>2</sup>
  - Processor: ~1 S/mm<sup>2</sup>
- Efficiency trades off with converter area overhead.





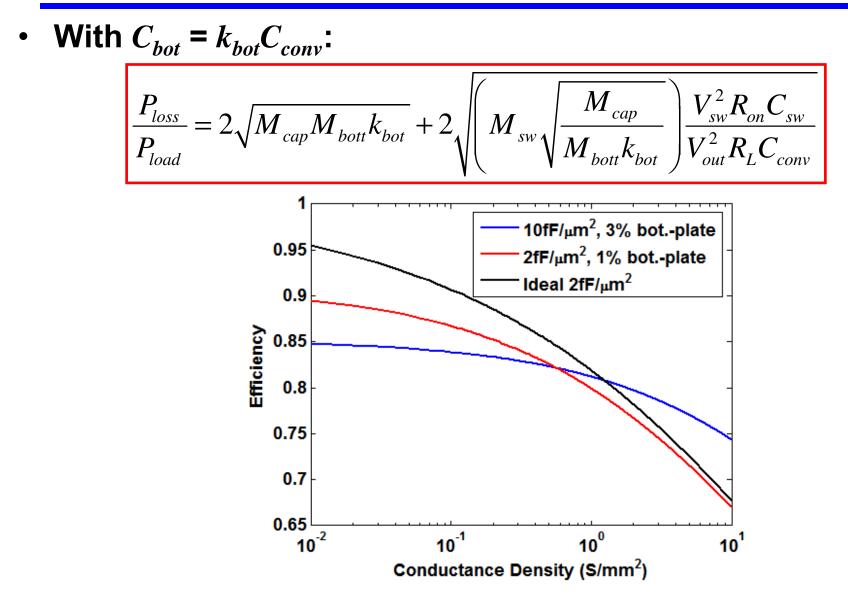
### **Side Note**



- Explicit decoupling capacitance usually required for supply integrity
- Can largely replace decap with converter
  - In order to fit, converter needs to deliver ~10X higher density than load



### **Impact of Bottom-Plate**



# Impact of Bottom-Plate cont'd

**Bottom plate sets min. loss:**  $P_{loss}/P_{load} \approx 2\sqrt{M_{cap}M_{bott}k_{bot}}$ • E.g., 2:1 step-down, 1% bottom plate  $\rightarrow$  10% loss



 In the limit of low power density:

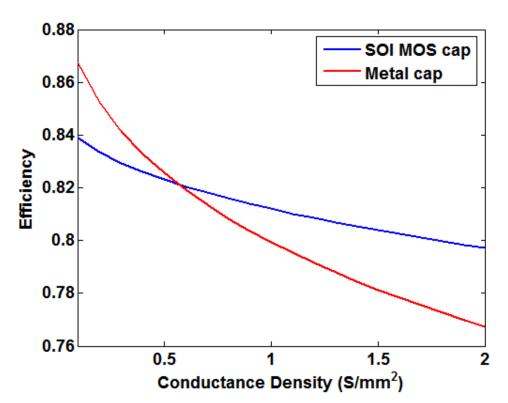
ullet

- Converter area does not affect efficiency
- Low parasitics more important than cap. density



# **Achievable Performance**

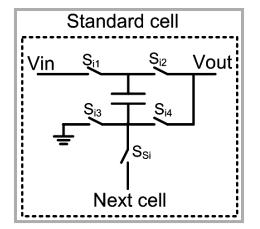
- 45nm, 2:1 converter:
  - 75% 80% efficiency at 1W/mm<sup>2</sup>
  - Even in standard CMOS
- Looks promising
  - Reminder: mobile device ~0.1W/mm<sup>2</sup>
  - But, only checked one conversion ratio so far...
- How to handle variable voltages?

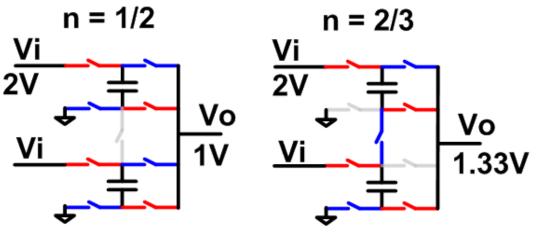


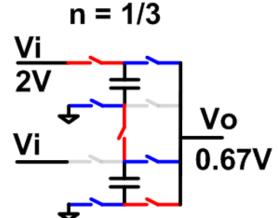


# SC "Standard Cell" Converter

- Integrated capacitors/switches easily partitioned
- "Standard cell" configuration sets conversion ratio



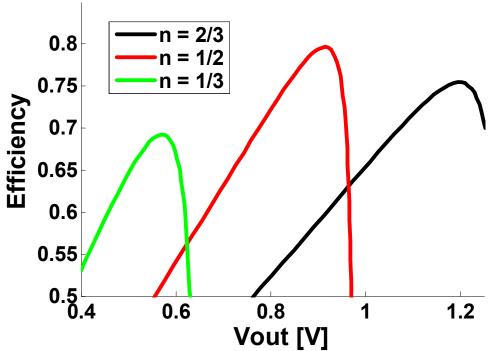






# **Efficiency vs. Conversion Ratio**

- Change topology,  $W_{sw}$ , and  $f_{sw}$ 
  - $R_{out} \sim 1/(Cf_{sw})$
  - Just like linear regulator
- Probably need only ~4-5 topologies
  - Clustered around 2:1
  - Watch out for switch drivers





## Prototype

- Implemented in 32nm SOI test-chip (w/AMD)
- MOS flying capacitors, 32-way interleaved

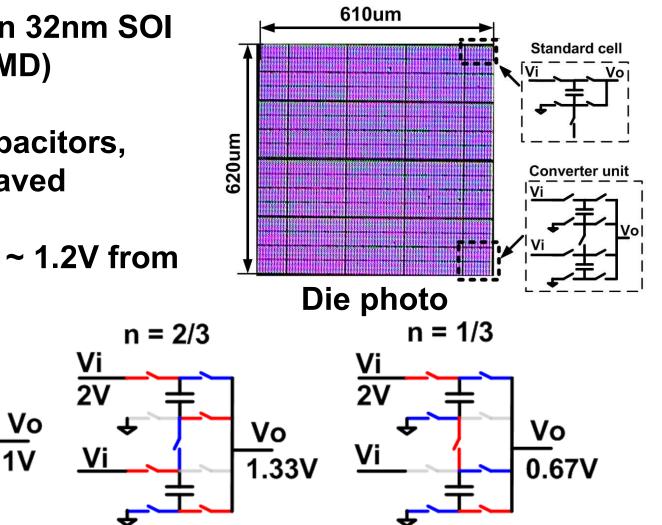
n = 1/2

<u>Vi</u>

Vi

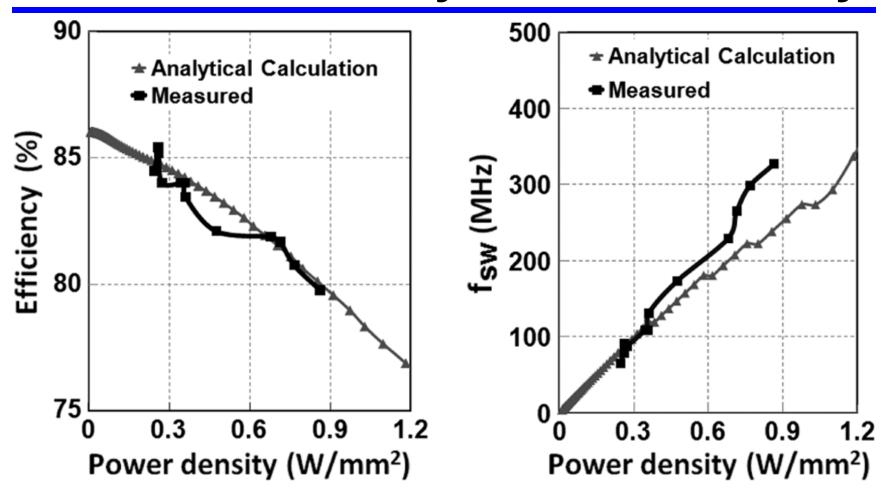
 $2\overline{V}$ 

 Supports 0.6V ~ 1.2V from 2V input



H.-P. Le, S. Sanders, and E. Alon, "Design Techniques for Fully Integrated Switched-Capacitor DC-DC Converters," *JSSC* Sept 2011.

Measured Efficiency vs. Power Density

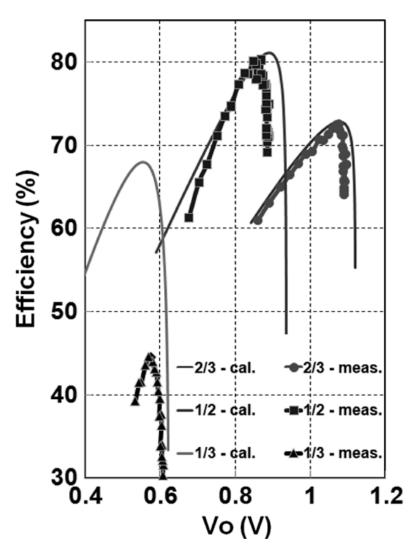


- Measured with n = 1/2 (Vi = 2V, Vo  $\approx 0.88V$ )
- Matches analysis: ~80% efficiency @ 0.86 W/mm<sup>2</sup>



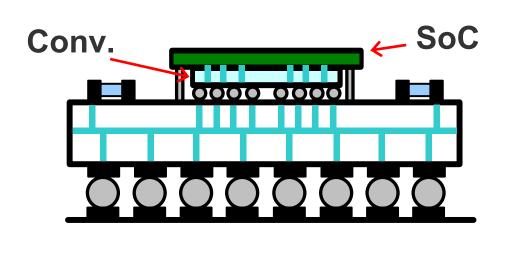
### Measured Efficiency vs. Topologies

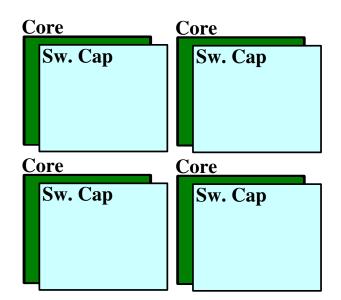
- All three topologies functional
  - (3:1 efficiency limited by breakdown)
- Efficiency still >70% for 0.75V – 1.15V Vo with 2V Vin



# Looking Forward: Leveraging 2.5/3D Integration



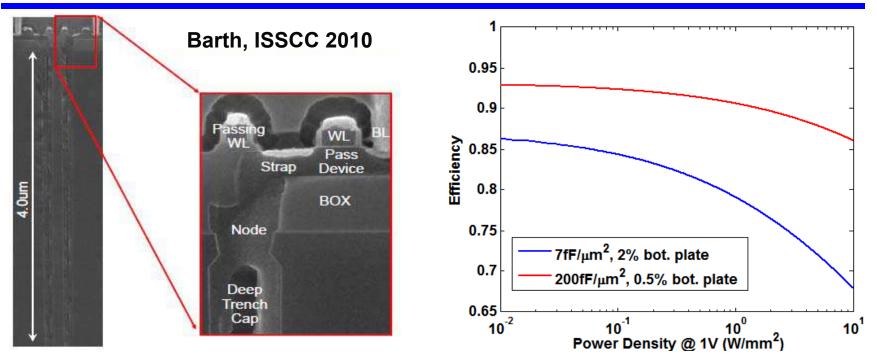




- Enables converter to use entire area over core
  - Mitigates efficiency vs. power density tradeoff
- Converter die can use older, lower-cost technology
  - While still meeting efficiency & density requirements

# Looking Forward: Dense Capacitors





- Dense capacitors already exist for DRAM/eDRAM
  - IBM eDRAM 2:1 converter\*: 90% efficiency @ 2.3A/mm<sup>2</sup>
- Opportunity to further leverage stacked DRAM

\*L. Chang *et al.*, "A Fully Integrated Switched-Capacitor 2:1 Voltage Converter with Regulation Capability and 90% Efficiency at 2.3A/mm<sup>2</sup>," *IEEE Symposium on VLSI Circuits*, Jun. 2010



### Summary

- Clear need for fully-integrated DC-DC converters
  - Multiple off-chip supplies costly, degrade impedance
- Switched-capacitor converters in standard CMOS can achieve:
  - In 2:1: ~80% efficiency @ 0.86 W/mm<sup>2</sup>
  - >70% efficiency for Vo from ~0.75V to 1.15V with
    Vi = 2V
- Low-cost technologies to enable even higher densities, efficiencies already exist



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